Intel® LXT16768/69/59 Multiplexer/DeMultiplexer Chipset

Product Overview

The Intel® LXT16768, LXT16769, and LXT16759 form a high-performance Mutiplexer/ DeMultiplexer (MUX/DeMUX) chipset for SONET OC-192 telecommunications systems, Optical Transport Network (OTN) systems with Enhanced Forward Error Correction (EFEC), Dense Wavelength Division Multiplexing (DWDM) for terrestrial and submarine transport systems, and fiber optic test equipment.

Manufactured using the BiCMOS7 process for optimal power and performance ratio, the Intel LXT16768/69 chipset ensures stability and reliability in Telco-class networking equipment. The 12.5Gbps chipset is perfectly aligned with the Intel® IXF30007 (EFEC) to provide 9dB gain in system sensitivity specifically for Ultra Long-Haul applications.

The Intel® LXT16768 DeMUX

This high-performance Serializer/Deserializer (SerDes) chipset features low-power dissipation and automatic operation adjustment in the 11–12Gbps and 12–13Gbps range. The LXT16768 has an integrated Clock and Data Recovery device (CDR) with 1:16 DeMUX and Limiting Amplifier (LIA).

The Intel LXT16768 has a DeMUX merged with a CDR and is fully compliant with the Optical Interface Forum's SFI-4 recommendation on common electrical interface between framers and SerDes for OC-192/STM 64.

The 12.5Gbps DeMUX transforms the serial data signals into 16-bit parallel data signals at a corresponding lower data rate.

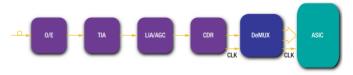


The Intel® LXT16769/59 MUX

The Intel LXT16769/59 features a 16:1 transmitter with integrated clock generation, Phase Locked Loop (PLL) circuits, and MUX with a 2-bit FIFO and dynamic phase alignment. The integrated functionalities in the devices ensure a simple board design, high input sensitivity, and optimal power consumption.

The Intel LXT16759 features a full or half line rate output clock. The fully integrated on-chip PLLs feature the unique dynamic phase alignment between ASIC and MUX and eliminate critical clock and data timing relations. Continuous handling of round-trip delay variations by the source synchronous clocking ensures easy external optimization of jitter.

(continued)



Typical receiver line card



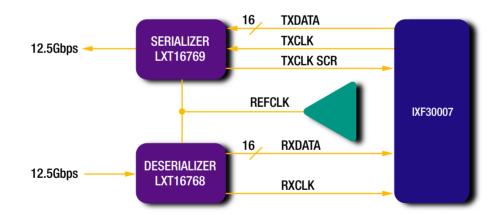
Typical transmitter line card



Intel has directed significant effort in the system and component design at maintaining precise, constant duration of the bit periods in the outgoing data stream. The Intel LXT16769/59 MUX converts a 16-bit parallel signal into one serial bit stream at a corresponding higher data rate.

The clock interconnections between the MUX and the data source, such as the framer, can be complex in high-speed applications. In high-speed clock operation for MUX, the input sampling clock must be in the phase to ensure correct loading of the data into the MUX so that input data can be sampled correctly. In addition, the internal high-speed clock used for shifting data to the laser must be as clean as possible to minimize the jitter in the output signal.

The SerDes chipset features high integration of functionalities which simplifies board design and saves cost. The lower power increases reliability and longer surrounding chip life, and superior sensitivity saves cost by eliminating the need for additional amplification parts. Optimal power performance ratios, excellent jitter performance, and support for enhanced FEC applications with up to 30 percent overhead processing makes the Intel LXT16768/16769 chipset ideal for Long-Haul/Ultra Long-Haul transmission.



System Application Layout

	LXT.	16768	DeML	JX
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	Benefits	Features	
umption	Optimal po	Dual Power Supply: +1.8V/+3.3V	
 Helps ensure stability and reliability, as well as longer surrounding chip life 		■ Power Dissipation: 0.85W	
processing from 10%-30% for cations	 Supports of extended (Features operation ranges: Option/01: 11–12Gbps Option/02: 12–13Gbps	
 LXT16768/69 and IXF30007 are key components for LH/ULH DWDM transmission systems 		 Interfaces to IXF30007 EFEC for support of up to 30% overhead processing for 9dB improved system sensitivity 	
tivity saves cost by eliminating nal amplification parts		Integrated LIA, CDR, and DeMux	
tem sensitivity with optimized symmetric input signal		Adjustable decision threshold control	
factor (13x13mm) supports e	 Small physical ph	132 PBGA Package	
ility between DeMUX (receiver)	Secures in and Frame	OIF SFI-4 Compliant Interface	
	Benefits	XT16769/59 MUX eatures	
and the second second			
and integration	Easy board	Single Power Supply: +3.3V	
d reliability, as well as longer		Single Power Supply: +3.3V Power Dissipation: 0.85W/0.95W	
d reliability, as well as longer processing from 10%–30% for	Ensures st surroundin		
d reliability, as well as longer processing from 10%–30% for	 Ensures st surroundin Supports c extended (LXT16768, 	Power Dissipation: 0.85W/0.95W Features operation ranges: Option/01: 11–12Gbps	
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n e l l	 Ensures st surroundin Supports c extended (LXT16768, LH/ULH D' Small phys reduced be 	Power Dissipation: 0.85W/0.95W Features operation ranges: Option/01: 11–12Gbps Option/02: 12–13Gbps Interfaces to IXF30007 EFEC for support of up to 30% overhead processing for 9dB improved system sensitivity 132 PBGA Package 2-bit FIFO combined with dynamic phase alignment	

11–12Gbps or 12–13Gbps receivers/transmitters Long-Haul/Ultra Long-Haul Optical Networking Equipment

- Extended Optical Transport Networking (OTU2V which is specifying higher than 7% overhead processing)
- DWDM line system

- Enhanced Forward Error Correction (EFEC)
- Terrestrial backbone telecommunication systems
- Submarine telecommunication systems
- Test equipment

Support Collateral/Tools

Item	Description	Order Number
■ Data Sheet	LXT16768 11–13Gbps Deserializer	250222-001
■ Data Sheet	LXT16769 11–13Gbps Serializer	250223-001
■ Data Sheet	LXT16759 11–13Gbps Serializer	250285-001
■ Data Sheet	LXD70768/69 Evaluation Board	250456-002

Intel Advantage

- Providing world-class optical components and solutions for multi-protocol and multi-rate networks
- Using leading-edge technologies and manufacturing capabilities to provide high-volume, low-cost optical offerings
- · Wide range of optical solutions that accelerate services deployment, reduce costs, and ease migration to higher bandwidth

Intel Access

Developer Web Site	http://developer.intel.com	
Networking Components Home Page	http://developer.intel.com/design/network	
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